

## 28-Bit to 56-Bit Registered Buffer With Address Parity Test One Pair to Four Pair Differential Clock PLL Driver

Check for Samples: [SN74SSQEC32882](#)

### FEATURES

- JEDEC SSTE32882
- 1-to-2 Register Outputs and 1-to-4 Clock Pair Outputs Support Stacked DDR3 RDIMMs
- CKE Powerdown Mode for Optimized System Power Consumption
- 1.5V/1.35V/1.25V Phase Lock Loop Clock Driver for Buffering One Differential Clock Pair (CK and  $\overline{\text{CK}}$ ) and Distributing to Four Differential Outputs
- 1.5V/1.35V/1.25V CMOS Inputs
- Checks Parity on Command and Address

### (CS-Gated) Data Inputs

- Configurable Driver Strength
- Uses Internal Feedback Loop
- Optimized Power Consumption

### APPLICATIONS

- DDR3 Registered DIMMs up to DDR3-1866
- DDR3L Registered DIMMs up to DDR3L-1600
- DDR3U Registered DIMMs up to DDR3U-1333
- Single-, Dual- and Quad-Rank RDIMM

### DESCRIPTION

This 1:2 or 26-bit 1:2 and 4-bit 1:1 registering clock driver with parity is designed for operation on DDR3 registered DIMMs with  $V_{DD}$  of 1.5 V, on DDR3L registered DIMMs with  $V_{DD}$  of 1.35 V and on DDR3U registered DIMMs with  $V_{DD}$  of 1.25 V.

All inputs are 1.5 V, 1.35V and 1.25 V CMOS compatible. All outputs are CMOS drivers optimized to drive DRAM signals on terminated traces in DDR3 RDIMM applications. The clock outputs  $Y_n$  and  $\overline{Y}_n$  and control net outputs  $D_x\text{CKEn}$ ,  $D_x\text{CSn}$  and  $D_x\text{ODTn}$  can be driven with a different strength and skew to optimize signal integrity, compensate for different loading and equalize signal travel speed.

The SN74SSQEC32882 has two basic modes of operation associated with the Quad Chip Select Enable ( $\overline{\text{QCSSEN}}$ ) input. When the  $\overline{\text{QCSSEN}}$  input pin is open (or pulled high), the component has two chip select inputs,  $\overline{\text{DCS0}}$  and  $\overline{\text{DCS1}}$ , and two copies of each chip select output,  $\overline{\text{QACS0}}$ ,  $\overline{\text{QACS1}}$ ,  $\overline{\text{QBCS0}}$  and  $\overline{\text{QBCS1}}$ . This is the "QuadCS disabled" mode. When the  $\overline{\text{QCSSEN}}$  input pin is pulled low, the component has four chip select inputs  $\text{DCS}[3:0]$ , and four chip select outputs,  $\text{QCS}[3:0]$ . This is the "QuadCS enabled" mode. Through the remainder of this specification,  $\overline{\text{DCS}}[n:0]$  will indicate all of the chip select inputs, where  $n=1$  for QuadCS disabled, and  $n=3$  for QuadCS enabled.  $\overline{\text{QxCS}}[n:0]$  will indicate all of the chip select outputs.

The device also supports a mode where a single device can be mounted on the back side of a DIMM. If  $\text{MIRROR}=\text{HIGH}$ , Input Bus Termination (IBT) has to stay enabled for all input signals in this case.

The SN74SSQEC32882 operates from a differential clock (CK and  $\overline{\text{CK}}$ ). Data are registered at the crossing of CK going HIGH, and  $\overline{\text{CK}}$  going LOW. This data could be either re-driven to the outputs or it could be used to access device internal control registers.

The input bus data integrity is protected by a parity function. All address and command input signals are added up and the last bit of the sum is compared to the parity signal delivered by the system at the input  $\overline{\text{PAR\_IN}}$  one clock cycle later. If they do not match the device pulls the open drain output  $\overline{\text{ERR\_OUT}}$  LOW. The control signals ( $\text{DCKE0}$ ,  $\text{DCKE1}$ ,  $\text{DODT0}$ ,  $\text{DODT1}$ ,  $\overline{\text{DCS}}[n:0]$ ) are not part of this computation.

The SN74SSQEC32882 implements different power saving mechanisms to reduce thermal power dissipation and to support system power down states. By disabling unused outputs the power consumption is further reduced.

The package is optimized to support high density DIMMs. By aligning input and output positions towards DIMM finger signal ordering and SDRAM ballout the device de-scrambles the DIMM traces allowing low cross talk design with low interconnect latency.

Edge controlled outputs reduce ringing and improve signal eye opening at the SDRAM inputs.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Table 1. ORDERING INFORMATION**

T <sub>CASE(max)</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE <sup>(2)</sup> PART NUMBER	TOP-SIDE MARKING
See <a href="#">Table 4</a>	176ZAL	Tape and Reel	SN74SSQEC32882ZALR	EC32882S

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).
- (2) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

## APPLICATION INFORMATION

### Vendor Specific SPD Content

SPD EEPROM on DDR3 RDIMMs has 3 vendor specific bytes for vendor and revision ID. This information can be sued by the system BIOS. The following table shows the correct values for SN74SSQEC32882.

**Table 2. Vendor specific SPD content for SN74SSQEC32882**

Byte	Value	Description
65	0x80	Vendor ID, part 1
66	0x97	Vendor ID, part 2
67	0x3D	Revision ID

### Application Reports

For additional Information on SN74SSQEC32882 DDR3 Register please review the following application reports:

- [DDR3 Register CMR programming](#)
- [DDR3 RDIMM SPD settings](#)
- [Yn phase shift on SN74SSQEA32882](#)
- [DDR3 Register IBT Measurement](#)

## ABSOLUTE MAXIMUM RATINGS

**Table 3. Absolute Maximum Ratings Over Operating Free-Air Temperature Range<sup>(1)</sup>**

PARAMETER		VALUE	UNIT
V <sub>DD</sub>	Supply voltage	–0.4 to +1.975	V
V <sub>I</sub>	Receiver input voltage	See <sup>(2)</sup> and <sup>(3)</sup>	V
V <sub>REF</sub>	Reference voltage	–0.4 to V <sub>DD</sub> + 0.5	V
V <sub>O</sub>	Driver output voltage	See <sup>(2)</sup> and <sup>(3)</sup>	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>DD</sub>	–50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>DD</sub>	±50 mA
I <sub>O</sub>	Continuous output current	0 < V <sub>O</sub> < V <sub>DD</sub>	±50 mA
I <sub>CCC</sub>	Continuous current through each V <sub>DD</sub> or GND pin		±100 mA
T <sub>stg</sub>	Storage temperature	–65 to +150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This value is limited to 1.975 V maximum.

**Table 4. Case Temperature vs Speed Node**

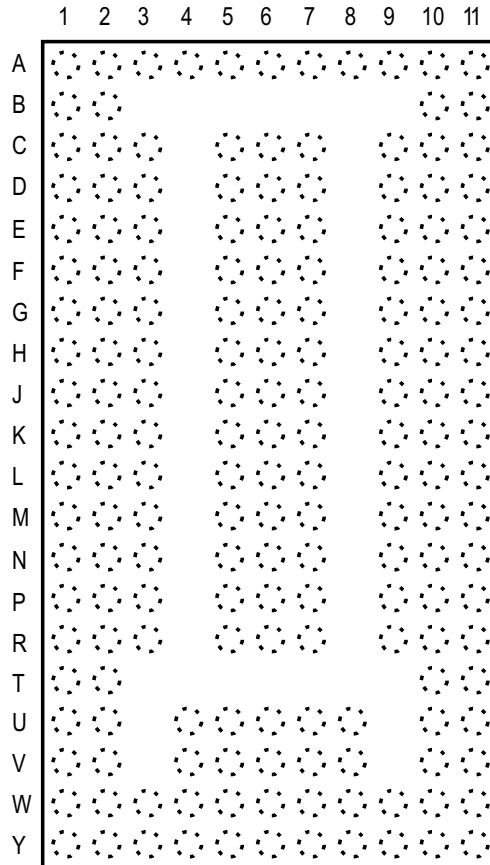
PARAMETER		DDR3-800	DDR3-1066	DDR3-1333	DDR3-1600	DDR3-1866	UNIT
T <sub>case(max)</sub>	Maximum case temperature <sup>(1)</sup>	+109	+108	+106	+103	+101	°C

- (1) The temperature values fit to JEDEC RAW cards A, B, and C. The user must keep T<sub>case</sub> below the specified values in order to keep the junction temperature below +125°C. Other combinations of features and termination resistors can require lower case temperature and extra cooling. These combinations depend on the specific application.

**PACKAGE INFORMATION**

**Pinout Configuration**

The package is a 8mm × 13.5mm 176-pin BGA with 0.65mm ball pitch in a 11 × 20 grid. The device pinout supports outputs on the outer two left and right columns to support easy DIMM signal routing. Corresponding inputs are placed in a way that two devices can be placed back to back for 4 Rank modules while the data inputs share the same vias. Each input and output is located close to an associated no ball position or on the outer two rows to allow low cost via technology combined with the small 0.65mm ball pitch.



**Figure 1. Pinout Configuration**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74SSQEC32882ZALR	ACTIVE	NFBGA	ZAL	176	2000	RoHS & Green	SNAGCU	Level-3-250C-168 HR	0 to 85	EC32882S	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

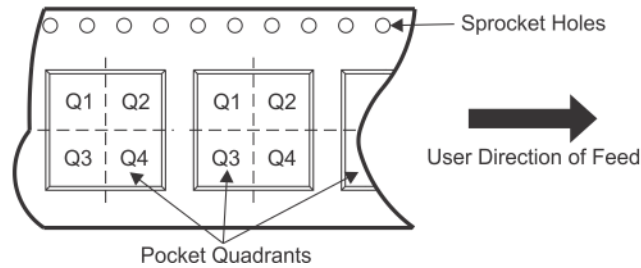
**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74SSQEC32882ZALR	NFBGA	ZAL	176	2000	330.0	24.4	8.3	13.8	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

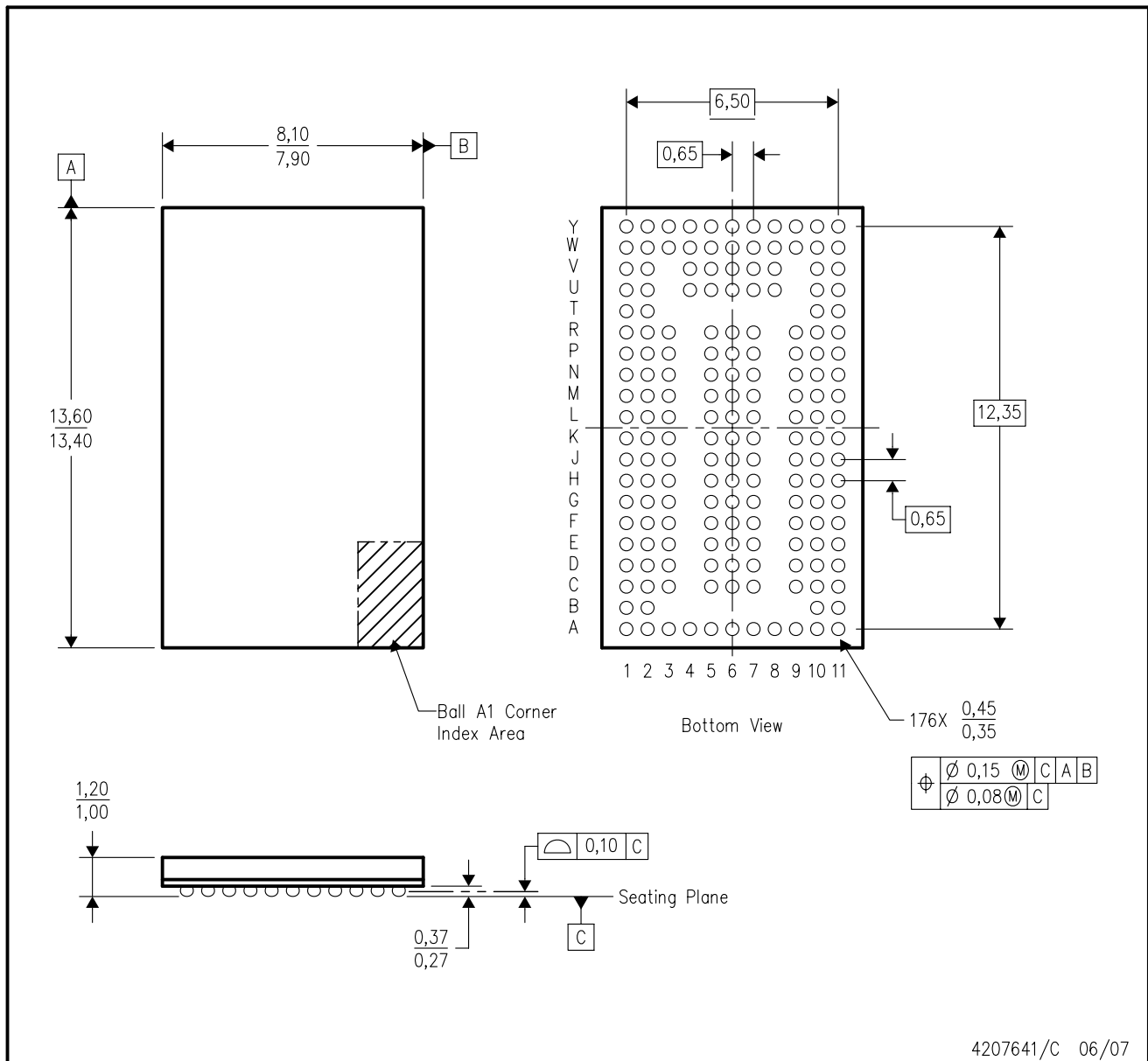


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74SSQEC32882ZALR	NFBGA	ZAL	176	2000	336.6	336.6	31.8

ZAL (R-PBGA-N176)

PLASTIC BALL GRID ARRAY



4207641/C 06/07

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. This package is lead-free.



## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<https://www.ti.com/legal/termsofsale.html>) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2021, Texas Instruments Incorporated